



Features

- ## General Description

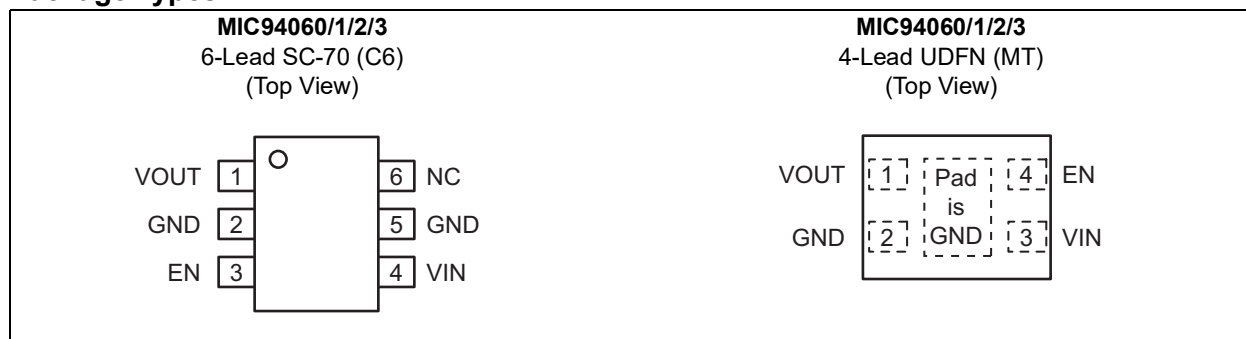
MIC94060-61 feature rapid turn-on while MIC94062-63 provide a slew-rate controlled soft-start turn-on of 800 μ s (typical) to prevent in-rush current from glitching supply rails.

MIC94060-63's operating voltage range makes them suitable for 1-cell Lithium ion and 2- to 3-cell NiMH/NiCad/Alkaline powered systems, as well as all 5V applications. Their low operating current of 2 μ A and low shutdown current of $<1 \mu$ A maximize battery life.

Applications

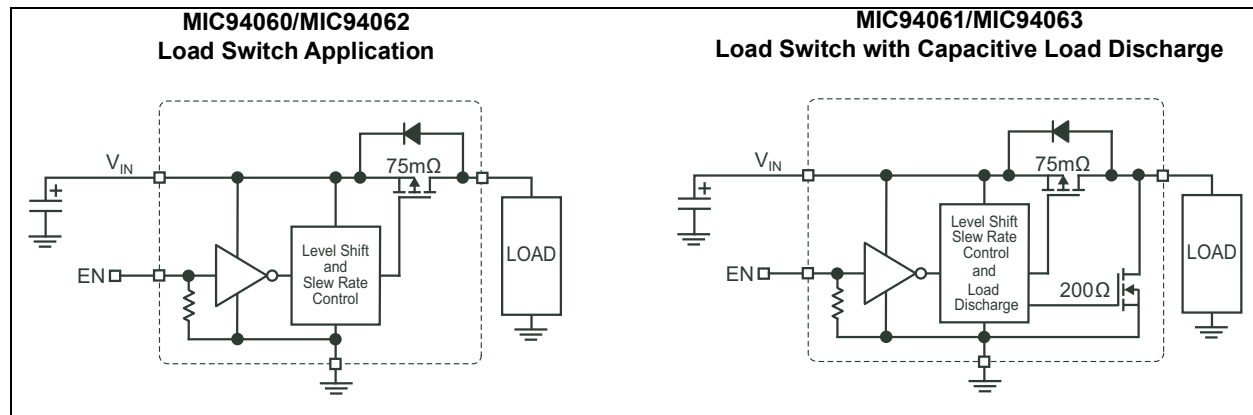
- Load Switch in Portable Applications
 - Cellular Phones
 - PDAs
 - MP3 Players
 - Digital Cameras
 - Portable Instrumentation
- Battery Switch-Over Circuits
- Level Translator

Package Types



MIC94060/1/2/3

Typical Application Circuits



1.0 ELECTRICAL CHARACTERISTICS

Absolute Maximum Ratings †

Input Voltage (V_{IN})	+6V
Enable Voltage (V_{EN})	+6V
Continuous Drain Current (I_D) (Note 1)	
$T_A = 25^\circ\text{C}$	$\pm 2\text{A}$
$T_A = 85^\circ\text{C}$	$\pm 1.4\text{A}$
Pulsed Drain Current (I_{DP}) (Note 2)	$\pm 6\text{A}$
Continuous Diode Current (I_S) (Note 3)	-50 mA
ESD Rating, HBM (Note 4)	4 kV

Operating Ratings ††

Input Voltage (V_{IN})	+1.7V to +5.5V
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† **Notice:** Stresses above those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operational sections of this specification is not intended. Exposure to maximum rating conditions for extended periods may affect device reliability.

†† **Notice:** The device is not guaranteed to function outside its operating ratings.

Note 1: With backside thermal contact to PCB.

2: Pulse width <300 μs with <2% duty cycle.

3: Continuous body diode current conduction (reverse conduction, i.e. V_{OUT} to V_{IN}) is not recommended.

4: Devices are ESD sensitive. Handling precautions recommended. Human body model, 1.5 k Ω in series with 100 pF.

ELECTRICAL CHARACTERISTICS

Electrical Characteristics: $V_{IN} = 5\text{V}$; $T_A = +25^\circ\text{C}$, **bold** values valid for $-40^\circ\text{C} \leq T_A \leq +85^\circ\text{C}$, unless noted.

Parameter	Symbol	Min.	Typ.	Max.	Units	Conditions
Enable Threshold Voltage	V_{EN_TH}	0.5	—	1.2	V	$V_{IN} = 1.8\text{V to } 4.5\text{V}$, $I_D = -250\text{ }\mu\text{A}$
		0.4	—	1.2		$V_{IN} = 1.7\text{V to } 4.5\text{V}$, $I_D = -250\text{ }\mu\text{A}$
Enable Input Current	I_{EN}	—	2	4	μA	$V_{IN} = V_{EN} = 5.5\text{V}$
OFF State Leakage Current	I_{VIN}	—	—	1	μA	$V_{IN} = +5.5\text{V}$, $V_{EN} = 0\text{V}$
P-Channel Drain to Source ON Resistance, SC-70 Package	$R_{DS(ON)}$	—	77	110	m Ω	$V_{IN}=+4.5\text{V}$, $I_D=-100\text{ mA}$, $V_{EN}=1.5\text{V}$
		—	85	115		$V_{IN}=+3.6\text{V}$, $I_D=-100\text{ mA}$, $V_{EN}=1.5\text{V}$
		—	100	140		$V_{IN}=+2.5\text{V}$, $I_D=-100\text{ mA}$, $V_{EN}=1.5\text{V}$
		—	145	200		$V_{IN}=+1.8\text{V}$, $I_D=-100\text{ mA}$, $V_{EN}=1.5\text{V}$
		—	155	215		$V_{IN}=+1.7\text{V}$, $I_D=-100\text{ mA}$, $V_{EN}=1.5\text{V}$
P-Channel Drain to Source ON Resistance, UDFN Package	$R_{DS(ON)}$	—	85	115	m Ω	$V_{IN}=+4.5\text{V}$, $I_D=-100\text{ mA}$, $V_{EN}=1.5\text{V}$
		—	100	140		$V_{IN}=+3.6\text{V}$, $I_D=-100\text{ mA}$, $V_{EN}=1.5\text{V}$
		—	145	200		$V_{IN}=+2.5\text{V}$, $I_D=-100\text{ mA}$, $V_{EN}=1.5\text{V}$
		—	155	215		$V_{IN}=+1.8\text{V}$, $I_D=-100\text{ mA}$, $V_{EN}=1.5\text{V}$
		—	165	225		$V_{IN}=+1.7\text{V}$, $I_D=-100\text{ mA}$, $V_{EN}=1.5\text{V}$
Turn-Off Resistance	R_{SHDN}	—	200	300	Ω	$V_{IN} = +3.6\text{V}$, $I_{TEST} = 1\text{ mA}$, $V_{EN} = 0\text{V}$, MIC94061, 63

MIC94060/1/2/3

ELECTRICAL CHARACTERISTICS (CONTINUED)

Electrical Characteristics: $V_{IN} = 5V$; $T_A = +25^{\circ}C$, **bold** values valid for $-40^{\circ}C \leq T_A \leq +85^{\circ}C$, unless noted.

Parameter	Symbol	Min.	Typ.	Max.	Units	Conditions
Dynamic						
Turn-On Delay Time	t_{ON_DLY}	—	0.85	1.5	μs	$V_{IN} = +3.6V$, $I_D = -100\text{ mA}$, $V_{EN} = 1.5V$, MIC94060, 61
		—	700	1200		$V_{IN} = +3.6V$, $I_D = -100\text{ mA}$, $V_{EN} = 1.5V$, MIC94062, 63
Turn-On Rise Time	t_{ON_RISE}	0.5	1	5	μs	$V_{IN} = +3.6V$, $I_D = -100\text{ mA}$, $V_{EN} = 1.5V$, MIC94060, 61
		500	800	1500		$V_{IN} = +3.6V$, $I_D = -100\text{ mA}$, $V_{EN} = 1.5V$, MIC94062, 63
Turn-Off Delay Time	t_{OFF_DLY}	—	100	200	ns	$V_{IN} = +3.6V$, $I_D = -100\text{ mA}$, $V_{EN} = 1.5V$, MIC94060, 61
		—	60	200		$V_{IN} = +3.6V$, $I_D = -100\text{ mA}$, $V_{EN} = 1.5V$, MIC94062, 63
Turn-Off Fall Time	t_{OFF_FALL}	—	60	100	ns	$V_{IN} = +3.6V$, $I_D = -100\text{ mA}$, $V_{EN} = 1.5V$, MIC94060, 61
		—	60	100		$V_{IN} = +3.6V$, $I_D = -100\text{ mA}$, $V_{EN} = 1.5V$, MIC94062, 63

TEMPERATURE SPECIFICATIONS

Parameters	Sym.	Min.	Typ.	Max.	Units	Conditions
Temperature Ranges						
Junction Temperature Range	T_J	-40	—	+125	$^{\circ}C$	—
Storage Temperature Range	T_S	-55	—	+150	$^{\circ}C$	—
Package Thermal Resistances						
Thermal Resistance, SC-70 6-Ld	θ_{JA}	—	240	—	$^{\circ}C/W$	—
Thermal Resistance, UDFN 4-Ld	θ_{JA}	—	172	—	$^{\circ}C/W$	—
Thermal Resistance, UDFN 4-Ld	θ_{JC}	—	134	—	$^{\circ}C/W$	—

Note 1: The maximum allowable power dissipation is a function of ambient temperature, the maximum allowable junction temperature and the thermal resistance from junction to air (i.e., T_A , T_J , θ_{JA}). Exceeding the maximum allowable power dissipation will cause the device operating junction temperature to exceed the maximum +125 $^{\circ}C$ rating. Sustained junction temperatures above +125 $^{\circ}C$ can impact the device reliability.

2.0 TYPICAL PERFORMANCE CURVES

Note: The graphs and tables provided following this note are a statistical summary based on a limited number of samples and are provided for informational purposes only. The performance characteristics listed herein are not tested or guaranteed. In some graphs or tables, the data presented may be outside the specified operating range (e.g., outside specified power supply range) and therefore outside the warranted range.

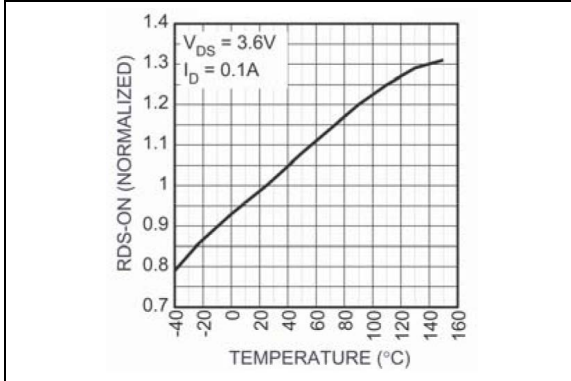


FIGURE 2-1: $R_{DS(ON)}$ Variance with Temperature.

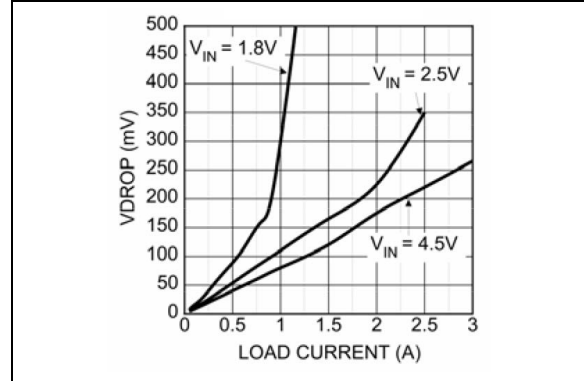


FIGURE 2-4: Voltage Drop vs. Load Current.

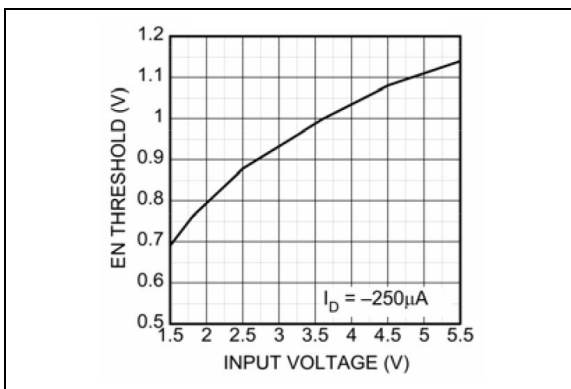


FIGURE 2-2: EN Threshold Voltage vs. Input Voltage.

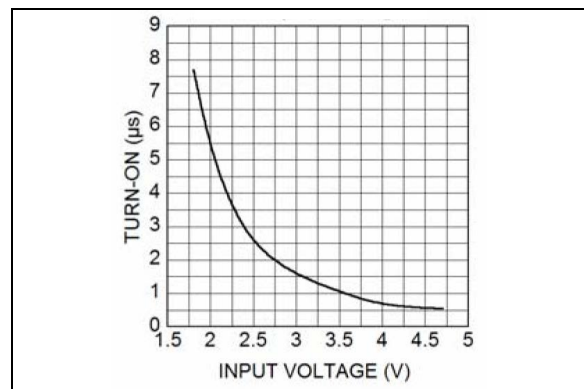


FIGURE 2-5: MIC94060/61 Turn-On Delay vs. Input Voltage.

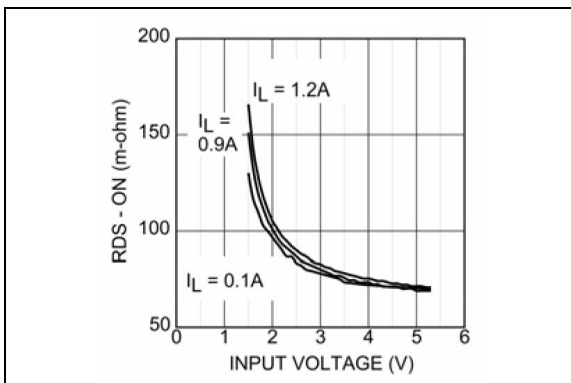


FIGURE 2-3: On-Resistance vs. Input Voltage.

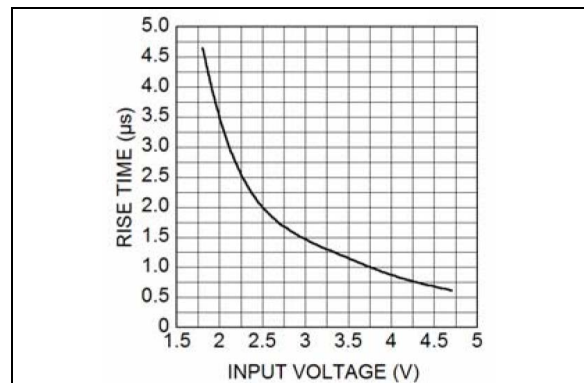


FIGURE 2-6: MIC94060/61 Rise Time vs. Input Voltage.

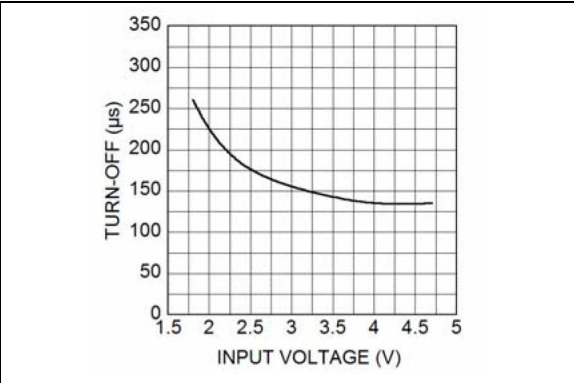


FIGURE 2-7: MIC94060/61 Turn-Off Delay vs. Input Voltage.

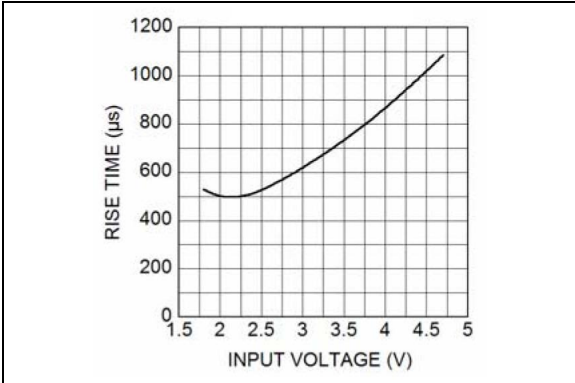


FIGURE 2-10: MIC94062/63 Rise Time vs. Input Voltage.

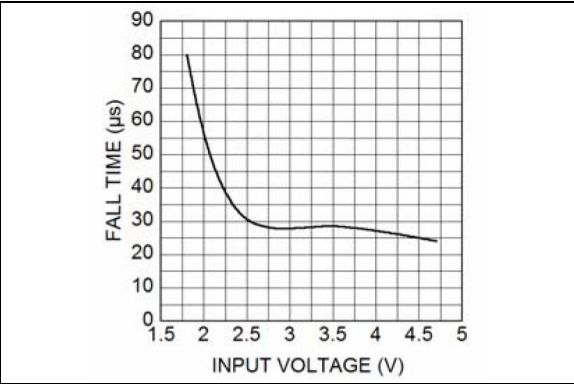


FIGURE 2-8: MIC94060/61 Fall Time vs. Input Voltage.

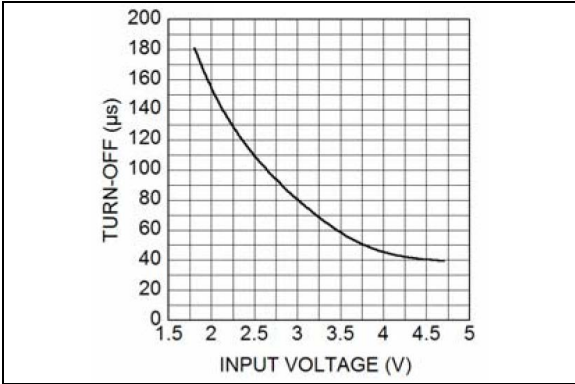


FIGURE 2-11: MIC94062/63 Turn-Off Delay vs. Input Voltage.

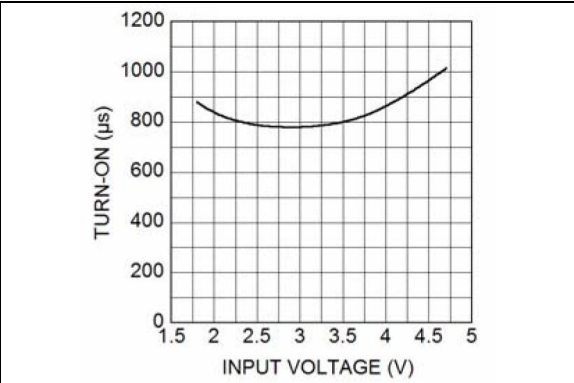


FIGURE 2-9: MIC94062/63 Turn-On Delay vs. Input Voltage.

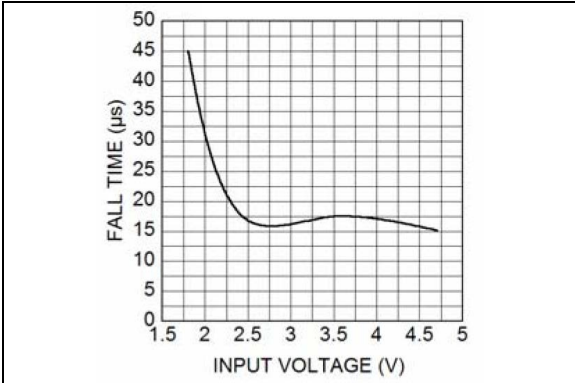


FIGURE 2-12: MIC94062/63 Fall Time vs. Input Voltage.

MIC94060

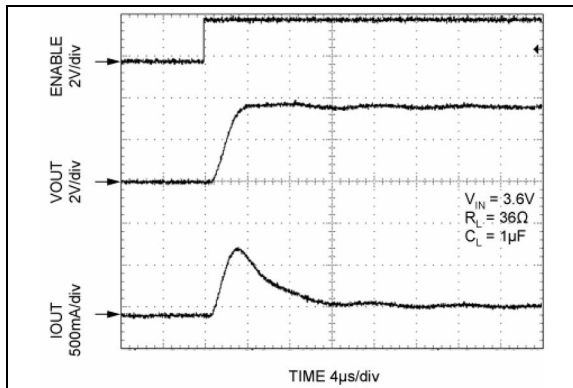


FIGURE 2-13: Turn-On/Turn-Off Timing.

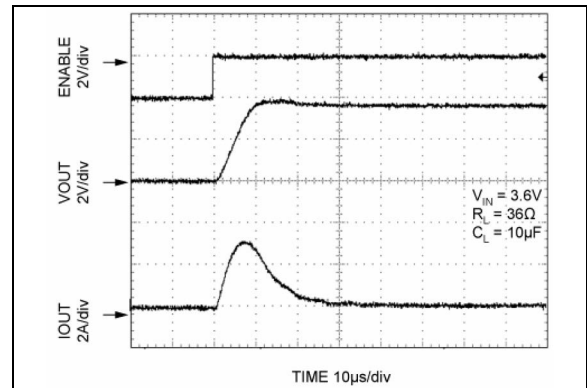


FIGURE 2-15: Turn-On/Turn-Off Timing.

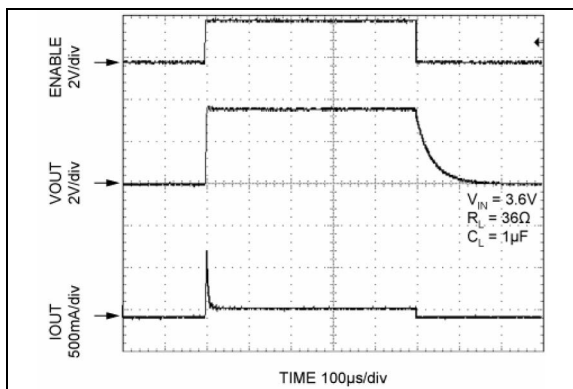


FIGURE 2-14: Turn-On/Turn-Off Timing.

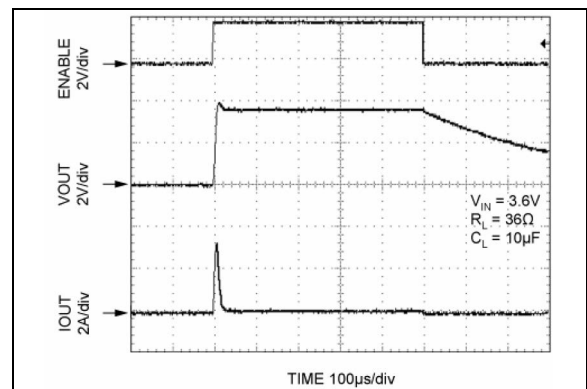


FIGURE 2-16: Turn-On/Turn-Off Timing.

MIC94061

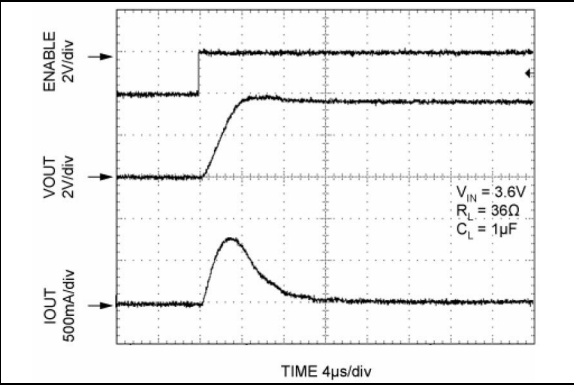


FIGURE 2-17: Turn-On/Turn-Off Timing.

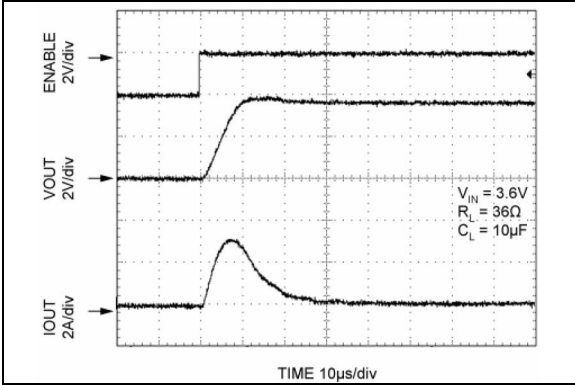


FIGURE 2-19: Turn-On/Turn-Off Timing.

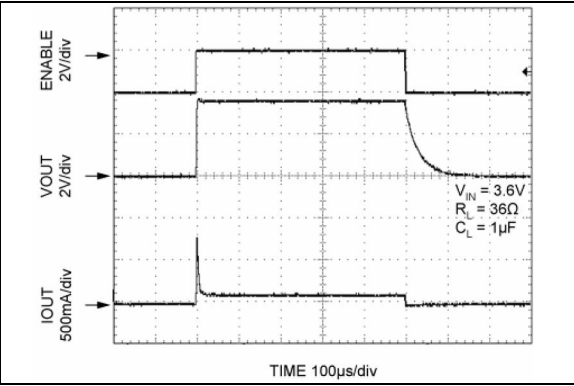


FIGURE 2-18: Turn-On/Turn-Off Timing.

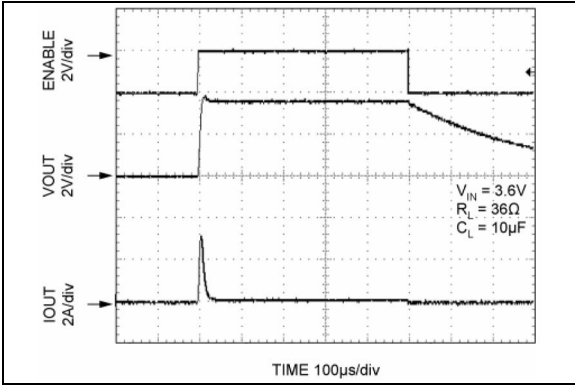


FIGURE 2-20: Turn-On/Turn-Off Timing.

MIC94062

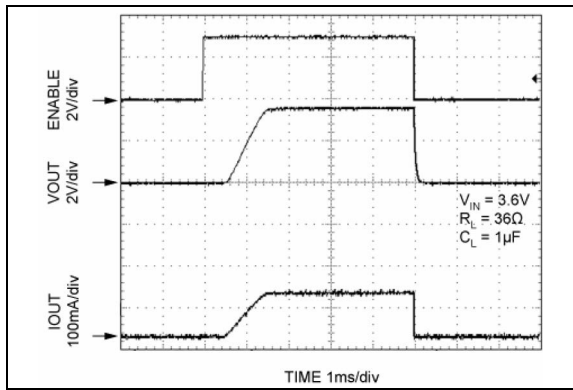


FIGURE 2-21: Turn-On/Turn-Off Timing.

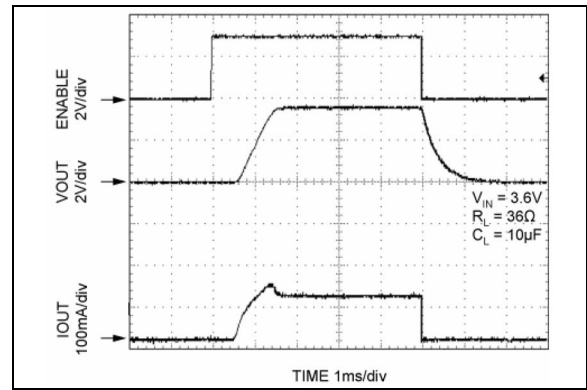


FIGURE 2-23: Turn-On/Turn-Off Timing.

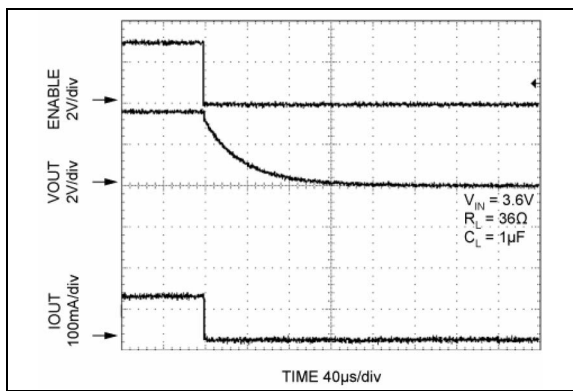


FIGURE 2-22: Turn-On/Turn-Off Timing.

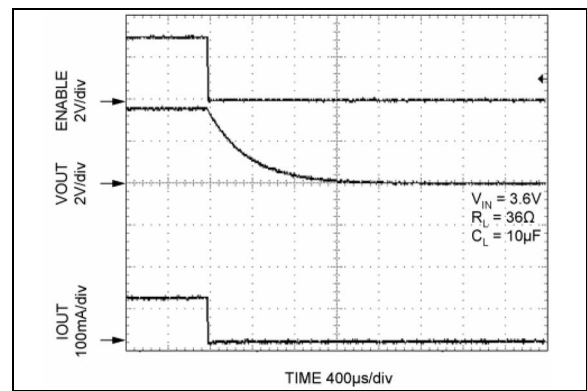


FIGURE 2-24: Turn-On/Turn-Off Timing.

MIC94063

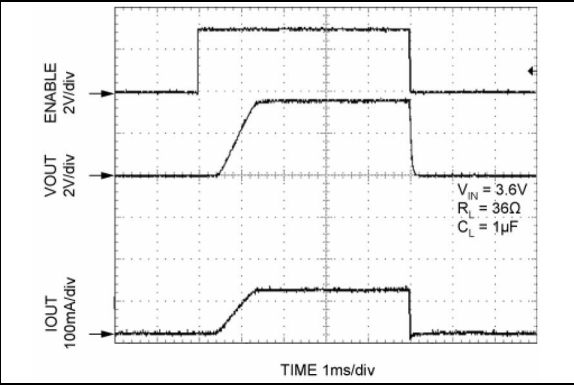


FIGURE 2-25: Turn-On/Turn-Off Timing.

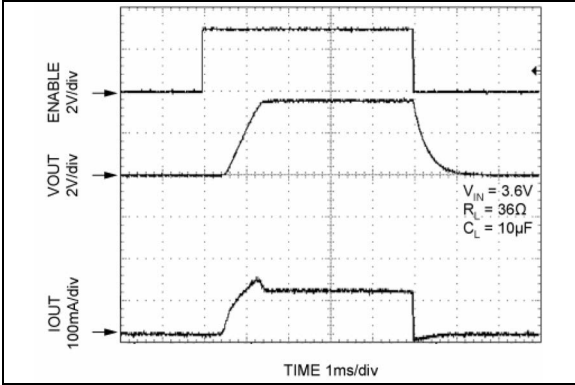


FIGURE 2-27: Turn-On/Turn-Off Timing.

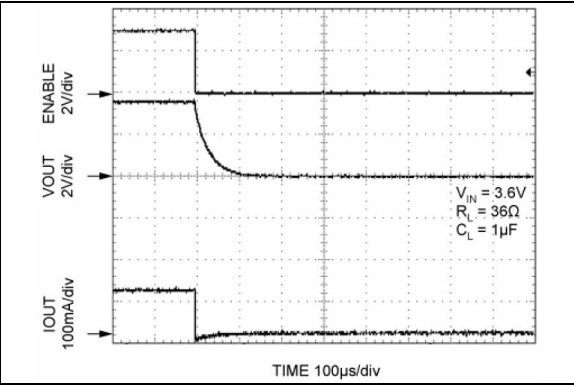


FIGURE 2-26: Turn-On/Turn-Off Timing.

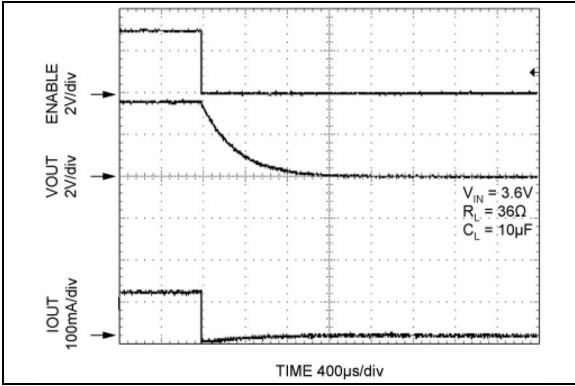


FIGURE 2-28: Turn-On/Turn-Off Timing.

3.0 PIN DESCRIPTIONS

The descriptions of the pins are listed in [Table 3-1](#).

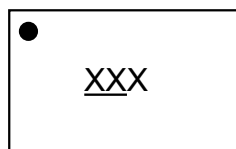
TABLE 3-1: PIN FUNCTION TABLE

Pin Number SC-70	Pin Number UDFN	Pin Name	Description
1	1	VOUT	Drain of P-channel MOSFET.
2, 5	2	GND	Ground and the backside pad (UDFN only) should both be connected to electrical ground.
4	3	VIN	Source of P-channel MOSFET.
3	4	EN	Enable (Input): Active-high CMOS compatible control input for switch A. Do not leave floating.
6	—	NC	No Internal Connection. A signal or voltage applied to this pin will have no effect on device operation.

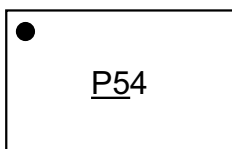
4.0 PACKAGING INFORMATION

4.1 Package Marking Information

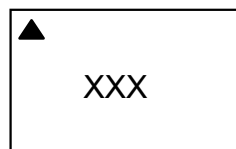
6-Lead SC70*



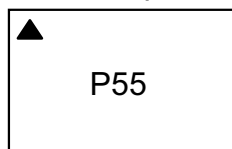
Example



4-Lead UDFN*



Example



Legend:	XX...X	Product code or customer-specific information
	Y	Year code (last digit of calendar year)
	YY	Year code (last 2 digits of calendar year)
	WW	Week code (week of January 1 is week '01')
	NNN	Alphanumeric traceability code
	(e3)	Pb-free JEDEC® designator for Matte Tin (Sn)
	*	This package is Pb-free. The Pb-free JEDEC designator ((e3)) can be found on the outer packaging for this package.
	•, ▲, ▼	Pin one index is identified by a dot, delta up, or delta down (triangle mark).
Note:	In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line, thus limiting the number of available characters for customer-specific information. Package may or may not include the corporate logo.	
	Underbar (_) and/or Overbar (¯) symbol may not be to scale.	

TABLE 4-1: MARKING CODES

Part Number	Marking Code	Soft-Start	Load Discharge
MIC94060YC6	P54	No	No
MIC94061YC6	P55	No	Yes
MIC94062YC6	P56	Yes	No
MIC94063YC6	P57	Yes	Yes
MIC94060YMT	P54	No	No
MIC94061YMT	P55	No	Yes
MIC94062YMT	P56	Yes	No
MIC94063YMT	P57	Yes	Yes

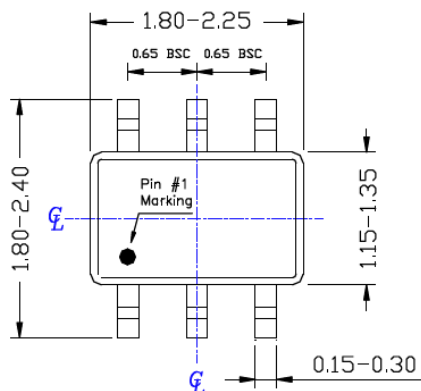
6-Lead SC-70 Package Outline & Recommended Land Pattern

TITLE

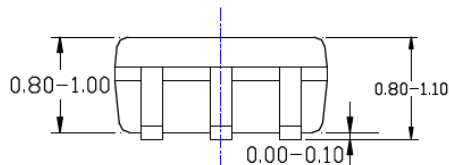
6 LEAD SC70 PACKAGE OUTLINE & RECOMMENDED LAND PATTERN

DRAWING # SC70-6LD-PL-1

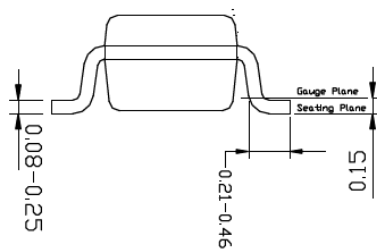
UNIT MM



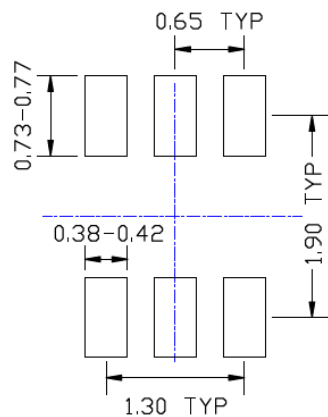
TOP VIEW



SIDE VIEW



END VIEW



RECOMMENDED
LAND PATTERN

NOTE:

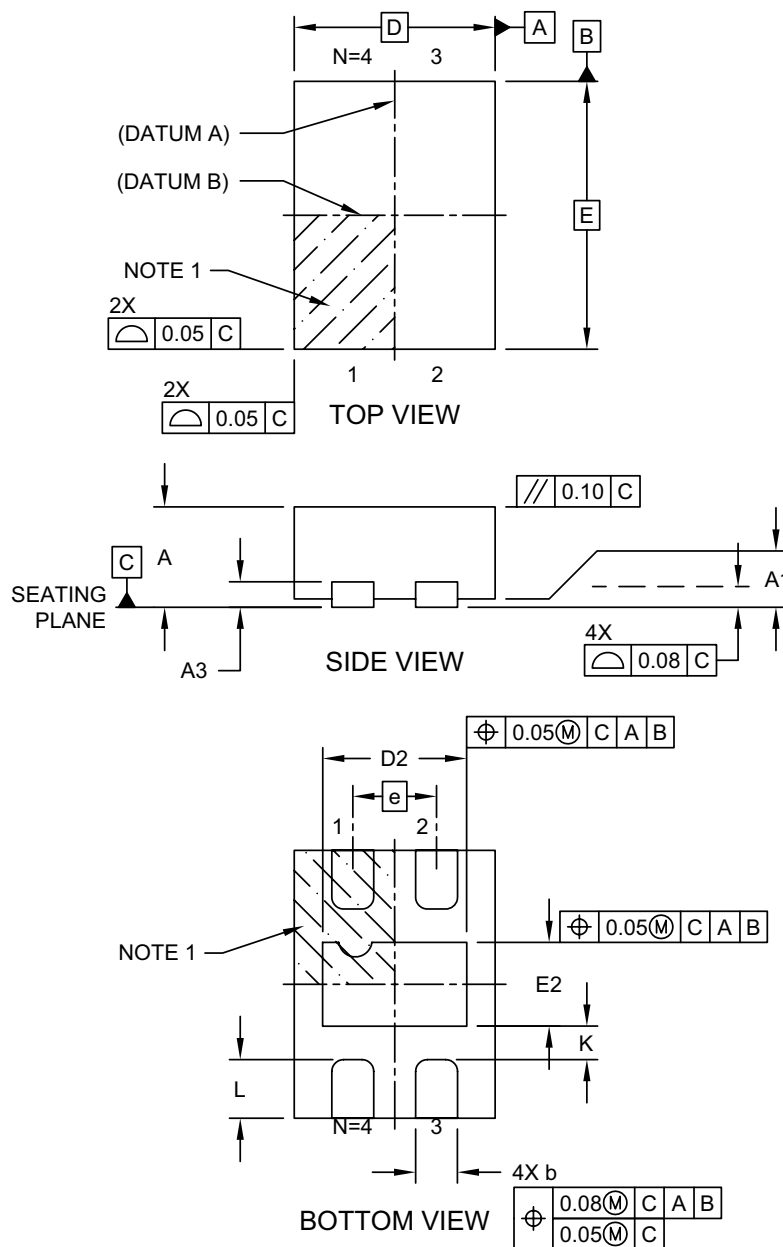
1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONS ARE INCLUSIVE OF PLATING.
3. DIMENSIONS ARE EXCLUSIVE OF MOLD FLASH & METAL BURR.

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>.

4-Lead UDFN Package Outline and Recommended Land Pattern

4-Lead Ultra Thin Dual Flat, No Lead Package (HGA) - 1.2x1.6x0.6 mm Body [UDFN] Micrel Legacy Package TMLF1216D-04L

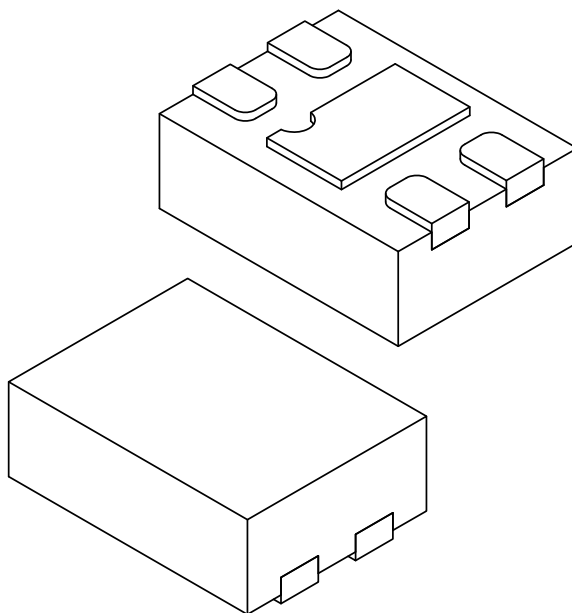
Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Microchip Technology Drawing C04-1152 Rev A Sheet 1 of 2

4-Lead Ultra Thin Dual Flat, No Lead Package (HGA) - 1.2x1.6x0.6 mm Body [UDFN] Micrel Legacy Package TMLF1216D-04L

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Terminals	N	4		
Pitch	e	0.50 BSC		
Overall Height	A	0.50	0.55	0.60
Standoff	A1	0.00	0.02	0.05
Terminal Thickness	A3	0.152 REF		
Overall Length	D	1.20 BSC		
Exposed Pad Length	D2	0.81	0.86	0.91
Overall Width	E	1.60 BSC		
Exposed Pad Width	E2	0.45	0.50	0.55
Terminal Width	b	0.20	0.25	0.30
Terminal Length	L	0.30	0.35	0.40
Terminal-to-Exposed-Pad	K	0.20	—	—

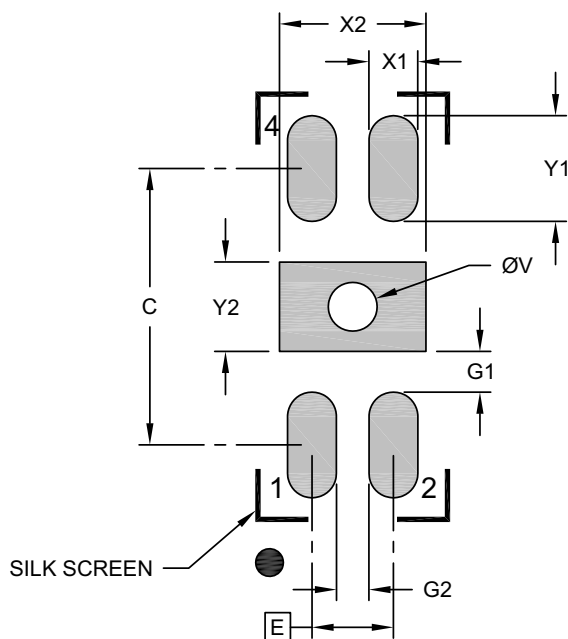
Notes:

- Pin 1 visual index feature may vary, but must be located within the hatched area.
- Package is saw singulated
- Dimensioning and tolerancing per ASME Y14.5M
 - BSC: Basic Dimension. Theoretically exact value shown without tolerances.
 - REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-1152 Rev A Sheet 2 of 2

4-Lead Ultra Thin Dual Flat, No Lead Package (HGA) - 1.2x1.6x0.6 mm Body [UDFN] Micrel Legacy Package TMLF1216D-04L

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



RECOMMENDED LAND PATTERN

Dimension Limits	Units	MILLIMETERS		
		MIN	NOM	MAX
Contact Pitch	E	0.50 BSC		
Optional Center Pad Width	X2			0.90
Optional Center Pad Length	Y2			0.55
Contact Pad Spacing	C		1.70	
Contact Pad Width (X4)	X1			0.30
Contact Pad Length (X4)	Y1			0.65
Contact Pad to Center Pad (X4)	G1	0.25		
Contact Pad to Contact Pad (X2)	G2	0.20		
Thermal Via Diameter	V		0.30	

Notes:

- Dimensioning and tolerancing per ASME Y14.5M
BSC: Basic Dimension. Theoretically exact value shown without tolerances.
- For best soldering results, thermal vias, if used, should be filled or tented to avoid solder loss during reflow process

Microchip Technology Drawing C04-3152 Rev A

APPENDIX A: REVISION HISTORY

Revision A (March 2021)

- Converted Micrel document MIC94060/1/2/3 to Microchip data sheet template DS20006517A.
- Minor grammatical text changes throughout.

Revision B (January 2022)

- Updated package marking drawing in [Section 4.1, Package Marking Information](#).

MIC94060/1/2/3

NOTES:

PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, contact your local Microchip representative or sales office.

Device	<u>X</u>	<u>XX</u>	<u>-XX</u>
Part No.	Junction Temp. Range	Package	Media Type
Device:	MIC94060: High Side Power Switch MIC94061: High Side Power Switch with Load Discharge MIC94062: High Side Power Switch with Soft-Start MIC94063: High Side Power Switch with Soft-Start and Load Discharge		
Junction Temperature Range:	Y = -40°C to +125°C		
Package:	C6 = 6-Lead SC-70 MT = 4-Lead 1.6 mm x 1.2 mm UDFN		
Media Type:	TR = 3,000/Reel (SC-70 Package) TR = 5,000/Reel (UDFN Package)		
Examples: a) MIC94060YC6-TR: MIC94060, -40°C to +125°C Temperature Range, 6-Lead SC-70, 3,000/Reel b) MIC94061YMT-TR: MIC94061, -40°C to +125°C Temperature Range, 4-Lead UDFN, 5,000/Reel c) MIC94062YC6-TR: MIC94062, -40°C to +125°C Temperature Range, 6-Lead SC-70, 3,000/Reel d) MIC94063YMT-TR: MIC94063, -40°C to +125°C Temperature Range, 4-Lead UDFN, 5,000/Reel e) MIC94060YMT-TR: MIC94060, -40°C to +125°C Temperature Range, 4-Lead UDFN, 5,000/Reel f) MIC94061YC6-TR: MIC94061 -40°C to +125°C Temperature Range, 6-Lead SC-70, 3,000/Reel Note 1: Tape and Reel identifier only appears in the catalog part number description. This identifier is used for ordering purposes and is not printed on the device package. Check with your Microchip Sales Office for package availability with the Tape and Reel option.			

MIC94060/1/2/3

NOTES:

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